I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON THE DATE INDICATED BELOW.

Date:

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: Chyh-Yih Chang

§ §

Conf. No.:

9385

Group Art Unit: 2822

Examiner:

Kiesha L. Rose

Application No.:

10/702,437

Filing Date:

November 7, 2003

Attorney Docket No.: 681954-166U2

Title: SUBSTRATE-BIASED SILICON DIODE FOR ELECTROSTATIC DISCHARGE

PROTECTION

RESPONSE TO RESTRICTION REQUIREMENT AND AMENDMENT

This paper is being submitted in response to the Office Action dated June 16, 2005 and is being timely filed within the shortened statutory period set for a response to the Office Action. No extension of time petition is believed to be due.

Amendment to the Title appears on page 2 of this paper.

Amendments to and Listing of the Claims begin on page 3 of this paper.

Remarks and Conclusion begin on page 8 of this paper.

-1-7436986 vl

Application No. 10/702,437 Reply to Office Action of June 16, 2005

Amendment to the Title:

In the Title section, replace the Title with the following amended Title:

SUBSTRATE-BIASED SILICON DIODE FOR ELECTROSTATIC DISCHARGE PROTECTION AND FABRICATION METHOD